

AMENDMENT TO THE CLAIMS

Claims 1-13 (Cancelled)

14. (Currently Amended) A semiconductor package, comprising:
- a leadframe comprising a plurality of leads segregated into two sets, the leads of each set being linearly aligned and arranged in spaced, generally parallel relation to each other such that each of the leads of one set extends in opposed relation to a respective one of the leads of the remaining set, each of the leads defining opposed, generally planar top and bottom sides;
- a semiconductor chip having a top surface and a bottom surface, the bottom surface partially overlapping and attached to the top side of at least one of the leads of each of the sets, the semiconductor chip being electrically connected to a portion of the top side of at least one of the leads which is positioned below the top surface; and
- a sealing material at least partially encapsulating the leadframe and the semiconductor chip, the sealing material having opposed, generally planar upper and lower surfaces such that the bottom side of each of the leads is generally co-planar with the lower surface of exposed within the sealing material.
15. (Previously Presented) The semiconductor package of Claim 14 wherein:
- each of the leads further defines an inner end and a notched surface which is disposed in opposed relation to the bottom side and extends to the inner end;
- each of the leads has a first thickness between the top and bottom sides which exceeds a second thickness between the bottom side and the notched surface; and
- the semiconductor chip partially overlaps and is attached to the notched surface of at least one of the leads of each of the sets.
16. (Previously Presented) The semiconductor package of Claim 15 wherein the semiconductor chip is electrically connected to the top side of at least one of the leads via a conductive wire which is covered by the sealing material.
17. (Previously Presented) The semiconductor package of Claim 15 wherein the semiconductor chip is electrically connected to the notched surface of at least one of the leads via a solder ball which is covered by the sealing material.

18. (Previously Presented) The semiconductor package of Claim 15 wherein the notched surfaces of the leads extend in generally co-planar relation to each other.

19. (Previously Presented) The semiconductor package of Claim 14 wherein:
each of the leads further defines an inner end and a notched surface which is disposed in opposed relation to the top side and extends to the inner end; and
each of the leads has a first thickness between the top and bottom sides which exceeds a second thickness between the top side and the notched surface.

20. (Previously Presented) The semiconductor package of Claim 19 wherein the semiconductor chip is electrically connected to the top side of at least one of the leads via a conductive wire which is covered by the sealing material.

21. (Previously Presented) The semiconductor package of Claim 14 wherein:
each of the leads further defines an outer end; and
the sealing material encapsulates the leadframe such that the outer end of each of the leads is exposed within the sealing material.

22. (Previously Presented) The semiconductor package of Claim 14 wherein the bottom sides of the leads extend in generally co-planar relation to each other.

23. (Previously Presented) The semiconductor package of Claim 14 wherein the top sides of the leads extend in generally co-planar relation to each other.

24. (Currently Amended) A leadframe comprising:
a peripheral tie bar; and
a plurality of leads ~~connected to~~ extending from the tie bar in isolation from each other and segregated into two sets, the leads of each set being linearly aligned and arranged in spaced, generally parallel relation to each other such that each of the leads of one set extends in opposed relation to a respective one of the leads of the remaining set, each of the leads defining:

opposed, generally planar top and bottom sides;
an inner end; and
a notched surface which is disposed in opposed relation to the bottom side and extends to the inner end;
each of the leads having a first thickness between the top and bottom sides which exceeds a second thickness between the bottom side and the notched surface.

25. (Previously Presented) The leadframe of Claim 24 wherein the notched surfaces of the leads extend in generally co-planar relation to each other.

26. (Previously Presented) The leadframe of Claim 24 wherein the bottom sides of the leads extend in generally co-planar relation to each other.

27. (Previously Presented) The leadframe of Claim 24 wherein the top sides of the leads extend in generally co-planar relation to each other.

28. (Currently Amended) A leadframe comprising:
a peripheral tie bar; and
a plurality of leads ~~connected to~~ extending from the tie bar in isolation from each other and segregated into two sets, the leads of each set being linearly aligned and arranged in spaced, generally parallel relation to each other such that each of the leads of one set extends in opposed relation to a respective one of the leads of the remaining set, each of the leads defining:

opposed, generally planar top and bottom sides;
an inner end; and
a notched surface which is disposed in opposed relation to the top side and extends to the inner end;
each of the leads having a first thickness between the top and bottom sides which exceeds a second thickness between the bottom side and the notched surface.

29. (Previously Presented) The leadframe of Claim 28 wherein the notched surfaces of the leads extend in generally co-planar relation to each other.

30. (Previously Presented) The leadframe of Claim 28 wherein the bottom sides of the leads extend in generally co-planar relation to each other.

31. (Previously Presented) The leadframe of Claim 28 wherein the top sides of the leads extend in generally co-planar relation to each other.